

承認書

SPECIFICATION FOR APPROVAL

Customer Name: 2144

Description Part No.:

Customer Part No.:

Sample No.:

DDY Part No.: SFEK3012A-

DRAWING		
MADE	CHECKED	APPROVED
王海玲	赵万虎	肖中华
DATE: 2023年8月24日		

CUSTOMER APPROVE



惠州市德立电子有限公司

HUI ZHOU DE LI ELECTRONICS CO., LTD

廣東省博羅縣洲際工業園梅園三路

NO.3 MEI YUAN ROAD,ZHOU JI INDUSTRIAL AREA,BOLUO COUNTY GUANGDONG

電話：15970768093 13640935893

傳真：0752-6207969

郵編：516100

Http: www.ddycoils.com

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1. Scope

This specification applies to the SFEK3012 Series of wire wound SMD power inductor.

2.PRODUCT IDENTIFICATION

SFEK 3012 □ - 1R5 □ - □
(1) (2) (3) (4) (5) (6)

(1) .Series name (产品品名)

(3) .Appearance shape (产品形状)

A: dodecagon (十二边形) : B: octagon (八边形)

(5) Tolerance (误差值)

M: $\pm 20\%$; N: $\pm 30\%$

(2) .Dimensions (产品尺寸)

(4) .Inductance value (电感值)

1R5: $1.5\mu\text{H}$ 221: $220\mu\text{H}$

(6) .Environmental status (环保状态)

LF- Lead free; HF-Halogen free;

FP-Free red phosphor.

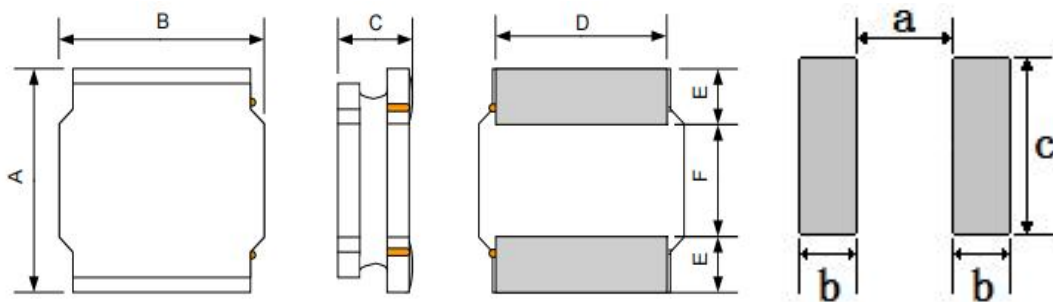
3. Electrical Characteristics

Please refer to Item 5.

- 1). Operating temperature range (individual chip without packing): $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$;
- 2). Storage temperature range (packaging conditions): $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$ and RH 70% (Max.);
- 3). Irms:DC current that causes the temperature rise ($\Delta T = 40^{\circ}\text{C}$) from 20°C ambient;
- 4). Isat: DC current at which the inductance drops approximate 30% from its value without current;
- 5). All test data is referenced to 20°C ambient;
- 6). Rated current: Isat or Irms, whichever is smaller;
- 7). Absolute maximum voltage: DC 25V;

4. Shape and Dimensions (Unit:mm)

shape: A



Recommended Land Pattern

Series	A	B	C	D	E	F	a Typ.	b Typ.	c Typ.
SFEK3012A	3.0 ± 0.2	3.0 ± 0.2	1.2 Max.	2.5 ± 0.2	0.9 Typ.	1.2 Typ.	1.00	1.10	2.7

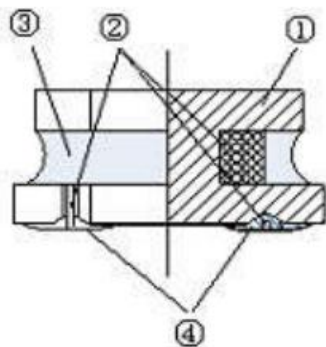
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6. Structure (The structure of product.)



NO	Components	Material
①	Core	soft magnetic metal
②	Wire	Polyurethane system enameled copper wire
③	Magnetic Glue	Epoxy resin and magnetic powder
④	Plating	AgNiSn or FeNiCu + Sn Alloy

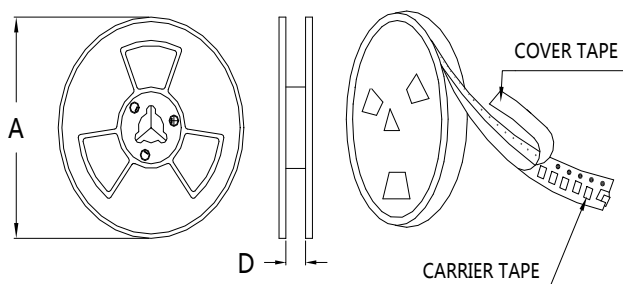
7. PACKAGING(unit: mm)

1.包装类型：编带装

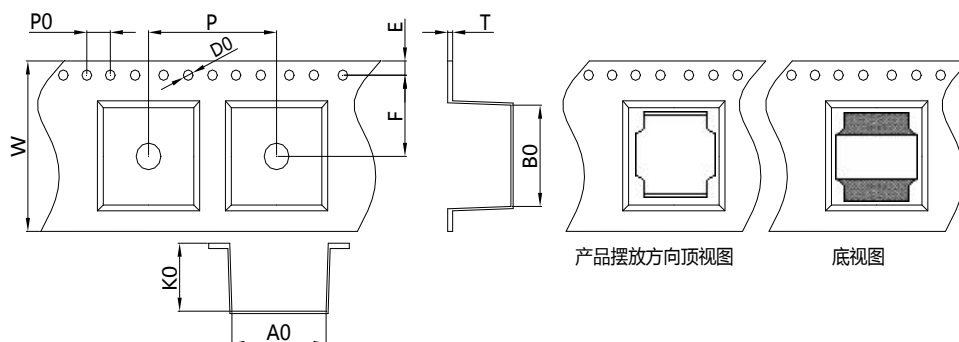
2.包装尺寸：

☐ 13" 盘

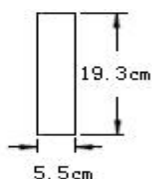
☒ 7" 盘



	13" 盘	7" 盘
A	$\Phi 330 \pm 2.0$	$\Phi 178 \pm 2.0$
D	8.5	



Item	W	A0	B0	K0	P	T	E	F	D0	P0
(mm)	8.0 ± 0.3	3.3 ± 0.15	3.3 ± 0.15	1.4 ± 0.1	4.0 ± 0.1	0.3 ± 0.1	1.75 ± 0.1	3.5 ± 0.1	1.5 ± 0.1	4.0 ± 0.1



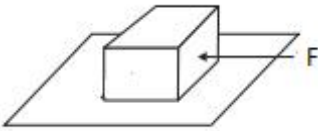
每卷	2000	Pcs
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每盒	4卷,共	8000	Pcs
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每箱	6盒,共	48000	Pcs
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8. RELIABILITY TEST

No.	TEST ITEM	SPECIFICATION	TEST CONDITION
1	High temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (N: Follow the product specification for the setting.) Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours
2	Low temperature Storage test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $-40^{\circ}\text{C} \pm 5^{\circ}\text{C}$ (M: Follow the product specification for the setting) Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours.
3	Humidity test	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	Temperature: $40 \pm 2^{\circ}\text{C}$, Humidity: $93 \pm 3\% \text{RH}$ Time : 96 ± 2 hours Place the samples for one hour at room temperature and test them within two hours
4	Solderability test	Terminals must have 95% minimum solder coverage	1. Dip pads in flux then dip in solder pot at $245 \pm 5^{\circ}\text{C}$ for 5 second. 2. Solder: lead free 3. Flux: rosin flux
5	Heat endurance of flow soldering	1. No significant defects in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta DCR/DCR \leq 10\%$	1. Refer to the above reflow curve and go through the reflow for twice. 2. The peak temperature : $260 \pm 0/-5^{\circ}\text{C}$
6	Vibration test	1. No significant defects in appearance. 2. No short and no open.	Apply frequency 10~55~10Hz and amplitude 1.5mm, 1 min/cycle in X Y and Z direction for 2 hours each. (total 6 hours)
7	Terminal strength push test	1. Applied force: 10N Duration: 10sec 2. Solder paste thickness: 0.12mm 3. Meet the above requirements without any loose termina	Solder the test samples to the PCB through 245°C reflow, apply a standard force on the side of the test samples for 10 seconds. 



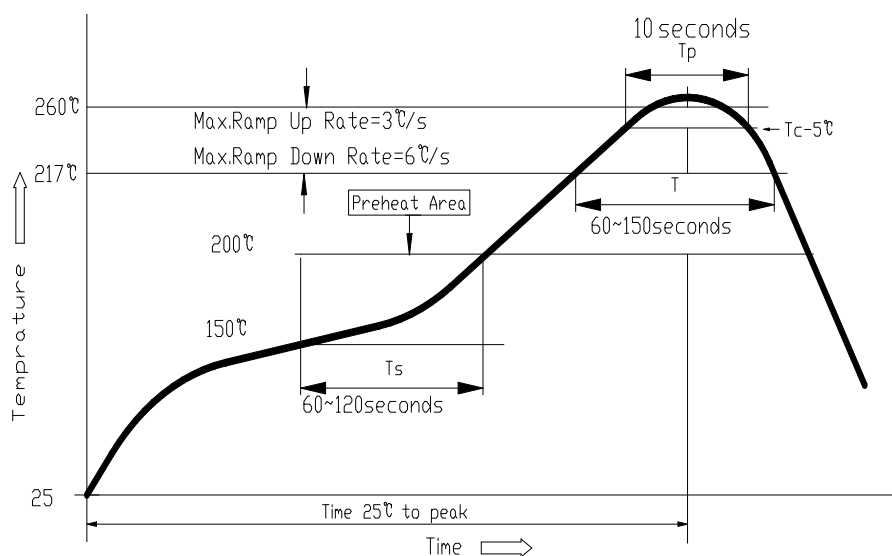
9. SOLDERING CONDITIONS

Applicable soldering process to the products is refl.

9.1 Soldering Materials

- (1) Solder: Sn-3.0Ag-0.5Cu
- (2) Flux: Use rosin-based flux, but not strongly acidic flux (with xhlorine exceeding 0.2wt%). Do not use water-soluble flux.

9.2 Reflow Soldering Profile



9.3 Soldering Iron

Reworking with electric soldering iron must preheating at 150°C for 1 minute is required, and do not directly touch the core with the tip of the soldering iron. The reworking soldering conditions are as follows.

- ① Temperature of soldering iron tip: 350°C;
- ② Soldering iron power output: ≤30W;
- ③ Diameter of soldering iron end: ≤1.0mm;
- ④ Soldering time: <3 s

